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## CLAIMS

1. A contact piece comprising a tungsten overlay (1) soldered onto a metallic support (3), characterized in that at least portions of the solder layer (2) and optionally the support are covered by a layer of a metal (4) which is less noble than tungsten.  
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2. The contact piece as claimed in claim 1, characterized in that the layer of the less noble metal is 0.1 to 20  $\mu\text{m}$  thick.  
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3. The contact piece as claimed in claim 2, characterized in that the layer of the less noble metal is 0.2 to 2  $\mu\text{m}$  thick.
4. The contact piece as claimed in claims 1 to 3, characterized in that the less noble metal is Sn, Zn, Mg or Al.  
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5. The contact piece as claimed in claim 4, characterized in that the less noble metal is Sn.  
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6. A method for the preparation of a contact piece as claimed in any one of claims 1 to 5, characterized in that a layer of a less noble metal than tungsten is applied onto the contact piece and subsequently base metal which may be present on the tungsten overlay is removed.  
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7. The method as claimed in claim 6, characterized in that the layer is applied via electroplating.
8. The method as claimed in claim 6 or 7, characterized in that the base metal is applied selectively onto the solder and the metallic support.  
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9. The method as claimed in any one of claims 6 to 8, characterized in that the re-exposure of the tungsten overlay is carried out by sliding grinding.
  
10. Use of the contact piece as claimed in any one of claims 1 to 5 as a horn contact or a relay contact.